

ZZ1 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

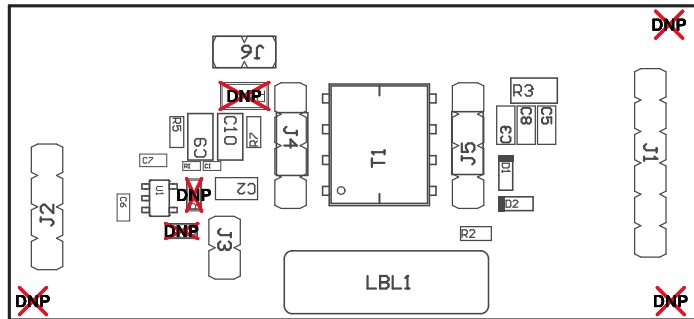
ZZ3 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

ZZ4 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ5 ■ Jumper/Shunt: SH-J4 on J4-PINs 2-3

ZZ6 ■ Jumper/Shunt: SH-J5 on J5-PINs 2-3

ZZ7 ■ Jumper/Shunt: SH-J6 on J6-PINs 1-2



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00349	REV: E1	SUN REV: Not In VersionControl
PLOT NAME = Top Assembly Drawing	GENERATED : 2/26/2015 10:07:56 AM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00349	REV: E1	SUN REV: Not In VersionControl
PLOT NAME = Bottom Assembly Drawing	GENERATED : 2/26/2015 10:07:57 AM	TEXAS INSTRUMENTS	

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